

ABSTRACT

APPARATUS FOR INCREASING COVERAGE OF SHIELDING GAS DURING WIRE BONDING

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A main body of an apparatus for delivering shielding gas during wire bonding of an electronic device has a through-hole in the main body which is sized for allowing a capillary tip of a bonding tool to be insertable through the main body
10 when performing wire bonding. At least one gas outlet located on a bottom surface of the main body adjacent to the through-hole is operative to direct an inert gas in a direction towards the electronic device. At least one gas inlet in the main body is operative to supply the inert gas to the through-hole and to the gas outlet.

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(FIG. 2)